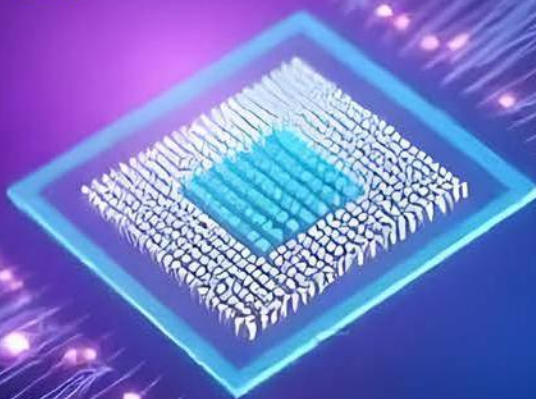


The Future of **IC Substrates and Beyond** Symposium 2025 **2025未来IC基板与 前瞻技术研讨会**



22.05.2025
**Sands Expo &
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The Future of IC Substrates and Beyond Symposium 2025

2025未來IC封装基板及前瞻技术研讨会

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Date: 22 May 2025 (Thursday)
Venue: Sands Expo & Convention Center, Singapore
Full Day Event: 9:00am – 5:30pm
日期：2025年5月22日（星期四）
地点：新加坡金沙会议展览中心
时间：上午9:00 – 下午5:30

AGENDA 议程

08:45 – 08:55	Registration 签到
08:55 – 09:00	Welcome 开幕致辞
09:00 – 09:50	Keynote: The Overview of Substrate and Interconnect Technologies 主题演讲：基板与互连技术全景解析 <i>Dr. Kelvin PUN, GMI Research Institute Vice President, Goertek Microelectronics Inc.</i>
09:50 – 10:40	Co-Design Considerations of Heterogeneous Integrated Package and Substrate 异构集成封装与基板的协同设计考量 <i>Prof. Gu-Sung KIM, Electronic Packaging Research Center, Kangnam University</i>
10:40 – 10:55	Break & Networking 休息与交流
10:55 – 11:45	Meeting AI Challenges-Large Package Solution and Warpage Management for Advance Substrates 应对AI挑战——大尺寸封装解决方案与先进基板翘曲管理 <i>Mr. Ifis ABDERRAZZEQ, TDI Director in Business Unit Micro Electronics, AT&S</i>
11:45 – 12:35	AI / HPC Advanced Substrate Technology Overview AI/HPC先进基板技术综述 <i>Mr. Youngseob SHIN, Amkor Technology</i>
12:35 – 14:05	Lunch Break 午休
14:05 – 14:55	SiC Power Semiconductors and Packaging Technology 碳化硅功率半导体及封装技术 <i>Mr. Ben KIM, Onsemi Korea</i>
14:55 – 15:45	Development and Characteristics of Advanced Packaging Substrate 先进IC封装基板的发展与特征探讨 <i>Dr. Rambo SUN, Bomin Electronics</i>
15:45 – 16:00	Break & Networking 休息与交流
16:00 – 16:50	Substrates Technology and Trend for High Performance Semiconductor Packages 高性能半导体封装基板技术趋势 <i>Dr. Chiwon HWANG, Samsung Electro-Mechanics</i>
16:50 – 17:30	Panel Discussion 论坛问答环节

This agenda is subject to change at the organizers' discretion. (Version 4)
本议程可能根据主办单位安排进行调整。如有差异请以英文为准。(版本号：V4)

The Future of IC Substrates and Beyond Symposium 2025

2025未來IC封装基板及前瞻技术研讨会

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Date 日期: 22 / 5 / 2025 (Thu 星期四)

Venue 地点: Sands Expo & Convention Center, Singapore 新加坡金沙会议展览中心

Participant fee 参加费用:

- ◆ Non-member 非会员: SG\$380 / HK\$2,260 / RMB2,260 (VAT included)
- ◆ HKPCA / KPCA / Semi Member 会员: SG\$350 / HK\$2,080 / RMB2,080 (VAT included)
- ◆ Early Bird Discount Rate for Member 早鸟优惠会员价:
(Register before 17 April 2025 through HKPCA / KPCA 在 2025 年 4 月 17 日前通过 HKPCA/KPCA 报名)
SG\$335 / HK\$1,990 / RMB1,990 (VAT included)

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Application Form 参加表格

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Bank A/C no 账户号码: 469-089601-838
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